

2SB1418, 2SB1418A

Silicon PNP epitaxial planar type darlington

For power amplification

Complementary to 2SD2138 and 2SD2138A

■ Features

- High forward current transfer ratio h_{FE}
- High-speed switching
- Allowing automatic insertion with radial tapering

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Collector-base voltage (Emitter open)	2SB1418	V_{CBO}	-60	V
	2SB1418A		-80	
Collector-emitter voltage (Base open)	2SB1418	V_{CEO}	-60	V
	2SB1418A		-80	
Emitter-base voltage (Collector open)		V_{EBO}	-5	V
Collector current		I_C	-2	A
Peak collector current		I_{CP}	-4	A
Collector power dissipation T_a = 25°C		P_C	15	W
			2.0	
Junction temperature		T_j	150	°C
Storage temperature		T_{stg}	-55 to +150	°C

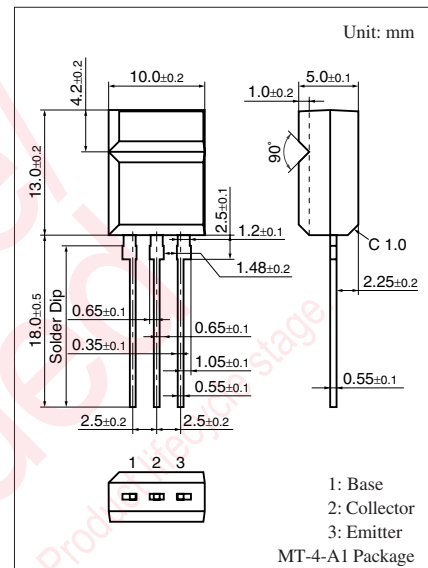
■ Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	2SB1418 2SB1418A	V_{CEO} $I_C = -30\text{ mA}, I_B = 0$	-60			V
			-80			
Base-emitter voltage	V_{BE}	$V_{CE} = -4\text{ V}, I_C = -2\text{ A}$			-2.8	V
Collector-base cutoff current (Emitter open)	2SB1418 2SB1418A	I_{CBO} $V_{CB} = -60\text{ V}, I_E = 0$ $V_{CB} = -80\text{ V}, I_E = 0$			-100	μA
					-100	
Collector-emitter cutoff current (Base open)	2SB1418 2SB1418A	I_{CEO} $V_{CE} = -30\text{ V}, I_B = 0$ $V_{CE} = -40\text{ V}, I_B = 0$			-100	μA
					-100	
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -5\text{ V}, I_C = 0$			-100	μA
Forward current transfer ratio	h_{FE1} h_{FE2}^*	$V_{CE} = -4\text{ V}, I_C = -1\text{ A}$ $V_{CE} = -4\text{ V}, I_C = -2\text{ A}$	1000			—
			1000		10000	
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -2\text{ A}, I_B = -8\text{ mA}$			-2.5	V
Transition frequency	f_T	$V_{CE} = -10\text{ V}, I_C = -0.5\text{ A}, f = 1\text{ MHz}$		20		MHz
Turn-on time	t_{on}	$I_C = -2\text{ A}, I_{B1} = -8\text{ mA}, I_{B2} = 8\text{ mA}$ $V_{CC} = -50\text{ V}$		0.2		μs
Turn-off time	t_{off}			2		μs

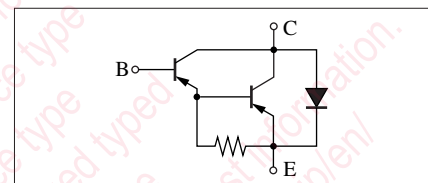
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

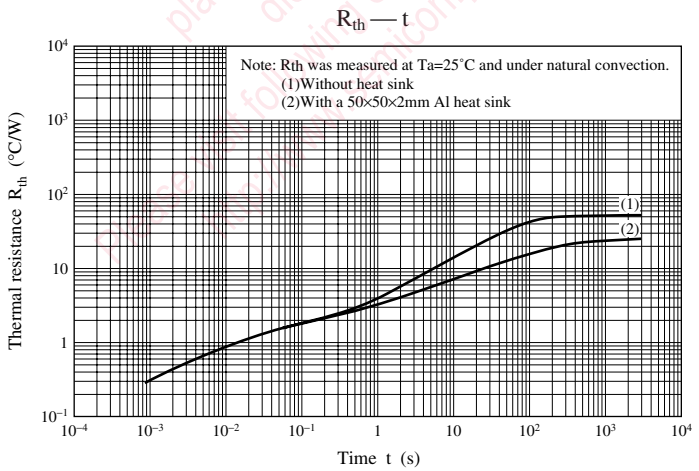
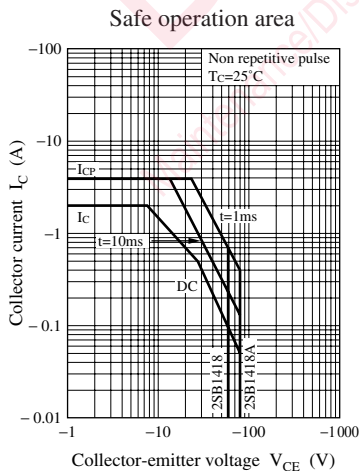
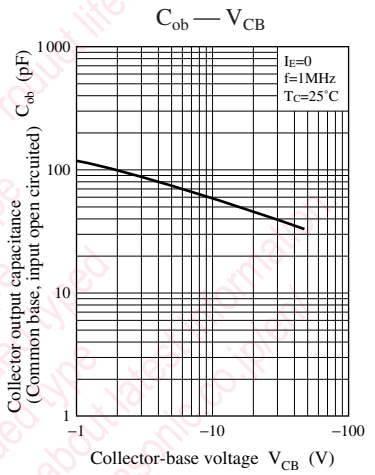
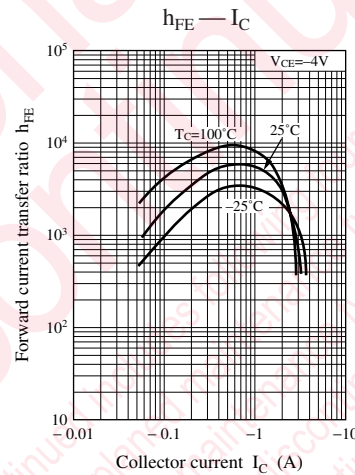
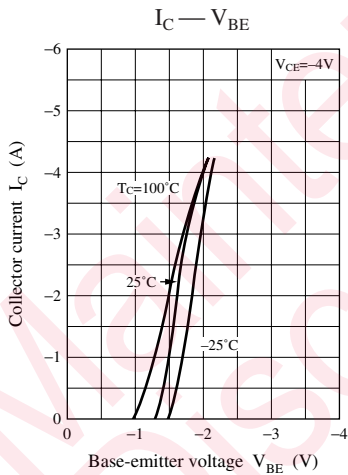
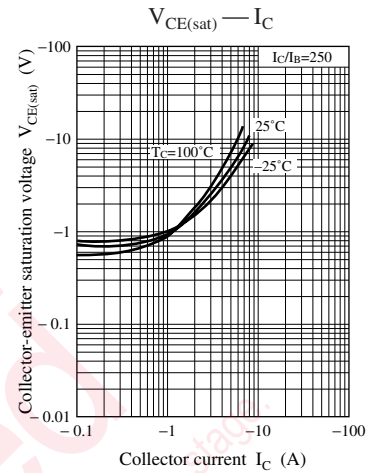
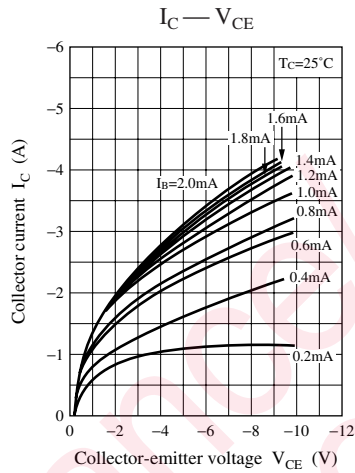
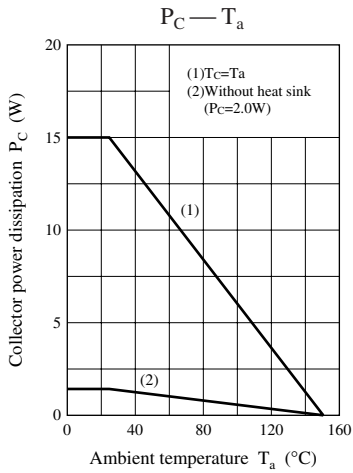
2. *: Rank classification

Rank	R	Q	P
h_{FE2}	1000 to 2500	2000 to 5000	4000 to 10000



Internal Connection





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